	CONNECTING CS INDUSTRIES® International and Pan	PC, Bannockb	urn, Illinois. A	Il rights reserved un ntions.	nder both	This docume level parts, t	ent is a declarat he declaration e	ion of the su encompasse	ubstances s all lowe	within the m r level materi	anufacture ials for wh	er listed ite	m. Note: if nufacturer	f the item is an as has engineering	sembly with lowe responsibility.
1752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					us Materia	als and Mfg Information				
Supplie	r Information														
Company	name*	Company unique ID			1	Unique ID Authority					Response Date*				
onsemi												2024-05-11			
Contact N	lame		Title - Contact]	Phone - Contact*					Email - Contact*			
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
Authorized Representative*			Title - Representative]	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA					Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item MC7812						Effective Date	Version]	Manufacturing Site		W	eight*	UOM	Unit Type
							2024-05-11 CNC			1:	365.61	mg	Each		
/Ianufa	cturing Proccess Informat	ion													
	Terminal Plating / Grid Array Material		Ferminal Base Alloy J-STD-020 M		-STD-020 MSI	L Rating	Peak Process Body Temperat		emperatu	ure Max Time at Peak Tem		Temperatu	re Numb	er of Reflow Cyc	eles
Matte Tin (Sn) - annealed		CU Alloy NA			0 C		30 sec		second	s 3					
omments	5														
or more	information regarding material of	composition	please refer to	page 3											

RoHS Material Composition Declaration				Declaration Type *	Detailed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et					
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in ifies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of				
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted				
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).						
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
Instructions: Complete all of the required fields on all pages of this form. Select the "Accepted" on the Supplier Acceptance drop-down. This will display the signature area. Digitally sign the declaration (if required by the Requester) and click on Submit Form to have the form returned to the Requester.									
Supplier Digital Signature	astislav Drska	Le							

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).										
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure		
Die	1.61	mg	Supplier	Silicon (Si)	7440-21-3		1.61	mg		
Die Attach	0.21	mg	А	Lead (Pb)	7439-92-1	7a	0.1995	mg		
			Supplier	Tin (Sn)	7440-31-5		0.0105	mg		
Lead Frame	677.24	mg	В	Nickel (Ni)	7440-02-0		0.3386	mg		
			Supplier	Iron (Fe)	7439-89-6		0.6772	mg		
			Supplier	Copper (Cu)	7440-50-8		676.0209	mg		
			Supplier	Phosphorus (P)	7723-14-0		0.2032	mg		
Mold Compound-Black	644.0	mg		Phenolic Resin	proprietary data		38.64	mg		
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		64.4	mg		
			Supplier	Carbon Black (C)	1333-86-4		3.22	mg		
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		48.3	mg		
			Supplier	Fused Silica (SiO2)	60676-86-0		489.44	mg		
Plating	42.4	mg	Supplier	Tin (Sn)	7440-31-5		42.4	mg		
Wire Bond - Cu	0.15	mg	Supplier	Copper (Cu)	7440-50-8		0.15	mg		

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3